

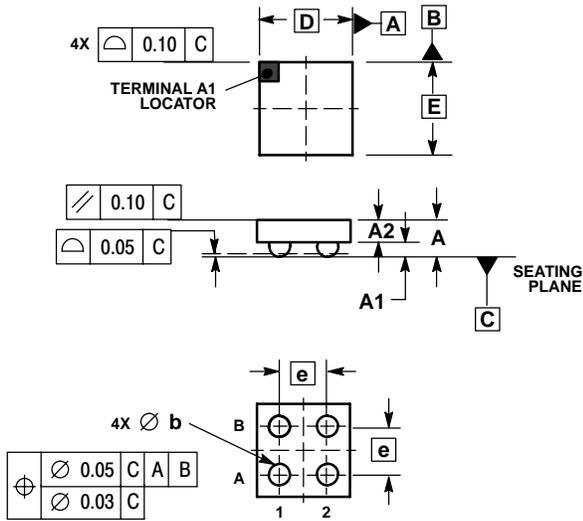
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SCALE 4:1

4 PIN FLIP-CHIP, 1.55X1.55
CASE 766AC-01
ISSUE O

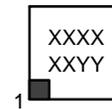
DATE 16 OCT 2003



- NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS IN COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.630
A1	0.250	0.310
A2	0.290	0.320
D	1.550 BSC	
E	1.550 BSC	
b	0.330	0.390
e	0.800 BSC	

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
 YY = Year
 WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	4 PIN FLIP-CHIP CSP 1.55X1.55, 0.80 PITCH	PAGE 1 OF 2

